

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Liquid Photo	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Liquid Ink	0.0254 mm	Purple	3.3	0
F.Cu	copper		0.0432 mm		1	0
Dielectric 1	prepreg	FR408HR 2113	0.2021 mm	FR4 natural	3.6	0.01
In1.Cu	copper		0.0175 mm		1	0
Dielectric 2	core	FR408-HR	0.9906 mm	FR4 natural	3.64	0.0098
In2.Cu	copper		0.0175 mm		1	0
Dielectric 3	prepreg	FR408HR 2113	0.2021 mm	FR4 natural	3.6	0.01
B.Cu	copper		0.0432 mm		1	0
B.Mask	Bottom Solder Mask	Liquid Ink	0.0254 mm	Purple	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Liquid Photo	0 mm	White	1	0

BOARD CHARACTERISTICS

Copper Layer Count:	4	Board Thickness:	1.5670 mm
Board overall dimensions:	52.5000 mm x 40.5000 mm	Min hole diameter:	0.3000 mm
Min track/spacing:	0.415 mm / 0.300 mm	Impedance Control:	Yes
Copper Finish:	ENIG	Plated Board Edge:	No
Castellated pads:	No		
Edge card connectors:	No		

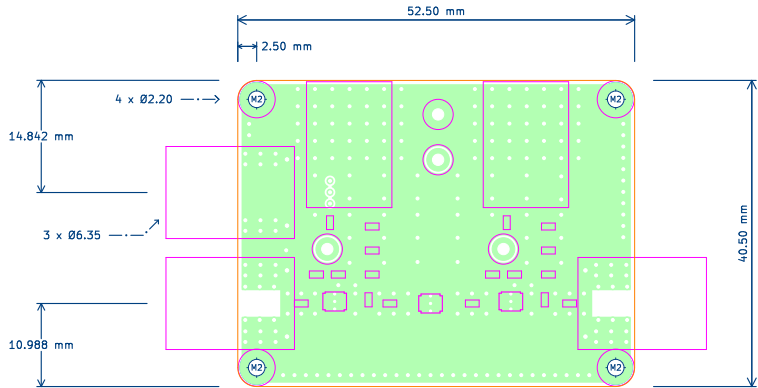
Notes:
LNA footprint is pin-compatible with PMA2-123LN+.

Remy Nguyen

Sheet:
File: 002.35.20.15.20-001-PCB-LNA.kicad_pcb

Title: RF-DFS Gain Circuit

Size: USLetter	Date: 2/23/2024	Rev: c
KiCad E.D.A. kicad 7.0.5		Id: 1/1



Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Liquid Photo	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Liquid Ink	0.0254 mm	Purple	3.3	0
F.Cu	copper		0.0432 mm		1	0
Dielectric 1	prepreg	FR408HR 2113	0.2021 mm	FR4 natural	3.6	0.01
In1.Cu	copper		0.0175 mm		1	0
Dielectric 2	core	FR408-HR	0.9906 mm	FR4 natural	3.64	0.0098
In2.Cu	copper		0.0175 mm		1	0
Dielectric 3	prepreg	FR408HR 2113	0.2021 mm	FR4 natural	3.6	0.01
B.Cu	copper		0.0432 mm		1	0
B.Mask	Bottom Solder Mask	Liquid Ink	0.0254 mm	Purple	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Liquid Photo	0 mm	White	1	0

BOARD CHARACTERISTICS

Copper Layer Count:	4	Board Thickness:	1.5670 mm
Board overall dimensions:	52.5000 mm x 40.5000 mm	Min hole diameter:	0.3000 mm
Min track/spacing:	0.415 mm / 0.300 mm	Impedance Control:	Yes
Copper Finish:	ENIG	Plated Board Edge:	No
Castellated pads:	No		
Edge card connectors:	No		

Notes:
LNA footprint is pin-compatible with PMA2-123LN+.

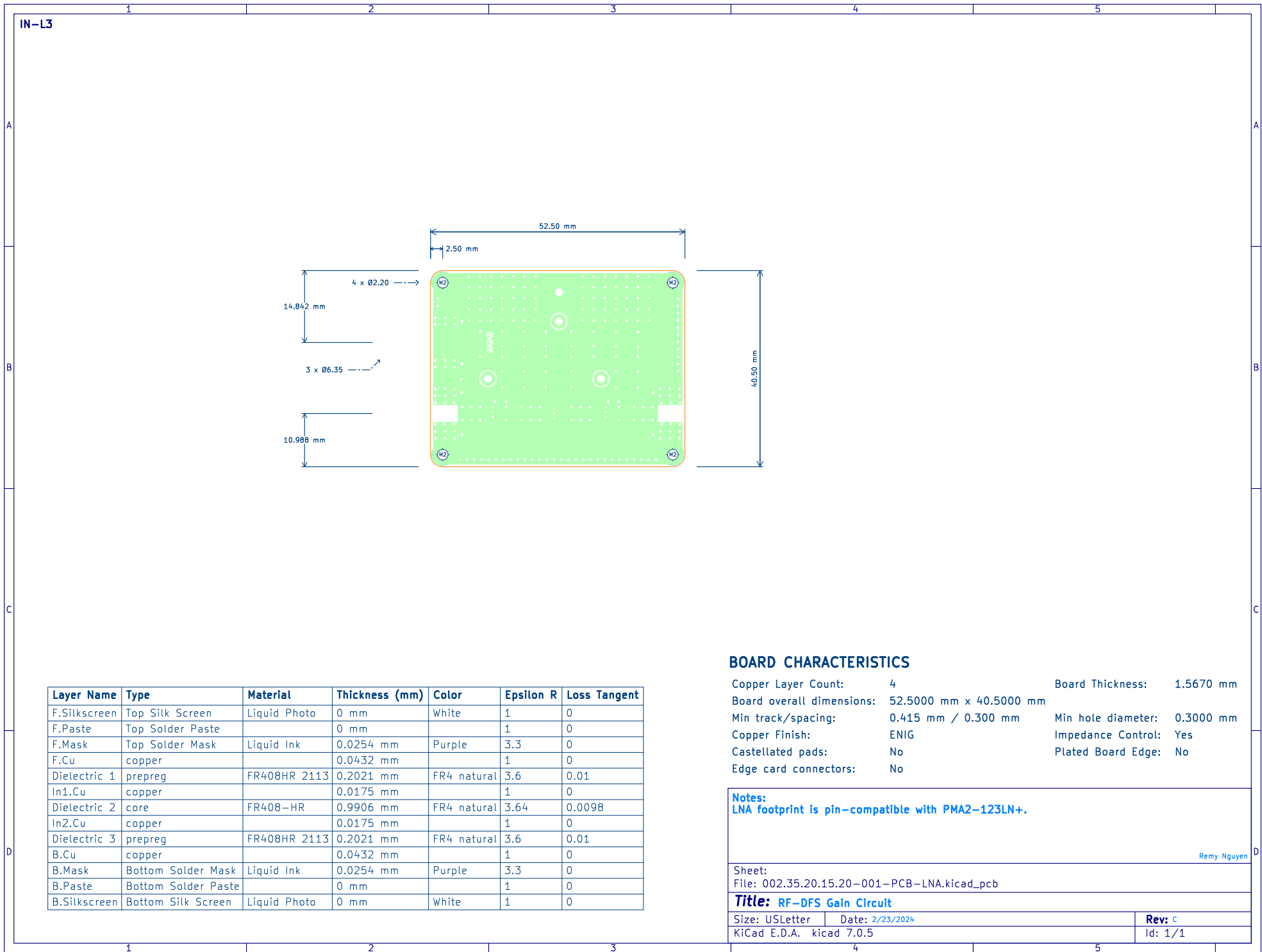
Remy Nguyen

Sheet:
File: 002.35.20.15.20-001-PCB-LNA.kicad_pcb

Title: RF-DFS Gain Circuit

Size: USLetter | Date: 2/23/2024
KiCad E.D.A. | kicad 7.0.5

Rev: c
Id: 1/1



BOT-L4

A

B

C

D

1

2

3

4

5

The diagram shows a rectangular PCB layout with overall dimensions of 52.50 mm by 40.50 mm. A 2.50 mm margin is indicated at the top left. The layout includes four circular mounting holes labeled M2, positioned at the corners. There are also several rectangular pads and traces. Dimensions for specific features are provided: 14.842 mm for the distance between two horizontal rows of pads, 10.988 mm for the distance between two vertical columns of pads, and 3 x Ø6.35 for three small circular features. A dimension of 4 x Ø2.20 is shown for a group of small circular features.

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Liquid Photo	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Liquid Ink	0.0254 mm	Purple	3.3	0
F.Cu	copper		0.0432 mm		1	0
Dielectric 1	prepreg	FR408HR 2113	0.2021 mm	FR4 natural	3.6	0.01
In1.Cu	copper		0.0175 mm		1	0
Dielectric 2	core	FR408-HR	0.9906 mm	FR4 natural	3.64	0.0098
In2.Cu	copper		0.0175 mm		1	0
Dielectric 3	prepreg	FR408HR 2113	0.2021 mm	FR4 natural	3.6	0.01
B.Cu	copper		0.0432 mm		1	0
B.Mask	Bottom Solder Mask	Liquid Ink	0.0254 mm	Purple	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Liquid Photo	0 mm	White	1	0

BOARD CHARACTERISTICS

Copper Layer Count:

Board overall dimensions:

Min track/spacing:

Copper Finish:

Castellated pads:

Edge card connectors:

4

52.5000 mm x 40.5000 mm

0.415 mm / 0.300 mm

ENIG

No

No

Board Thickness:

Min hole diameter:

Impedance Control:

Plated Board Edge:

1.5670 mm

0.3000 mm

Yes

No

Notes:

LNA footprint is pin-compatible with PMA2-123LN+.

Remy Nguyen

Sheet:

File: 002.35.20.15.20-001-PCB-LNA.kicad_pcb

Title: RF-DFS Gain Circuit

Size: USLetter

Date: 2/23/2024

Rev: C

KiCad E.D.A. kicad 7.0.5

Id: 1/1

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Liquid Photo	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Liquid Ink	0.0254 mm	Purple	3.3	0
F.Cu	copper		0.0432 mm		1	0
Dielectric 1	prepreg	FR408HR 2113	0.2021 mm	FR4 natural	3.6	0.01
In1.Cu	copper		0.0175 mm		1	0
Dielectric 2	core	FR408-HR	0.9906 mm	FR4 natural	3.64	0.0098
In2.Cu	copper		0.0175 mm		1	0
Dielectric 3	prepreg	FR408HR 2113	0.2021 mm	FR4 natural	3.6	0.01
B.Cu	copper		0.0432 mm		1	0
B.Mask	Bottom Solder Mask	Liquid Ink	0.0254 mm	Purple	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Liquid Photo	0 mm	White	1	0

Copper Layer Count:	4	Board Thickness:	1.5670 mm
Board overall dimensions:	52.5000 mm x 40.5000 mm		
Min track/spacing:	0.415 mm / 0.300 mm	Min hole diameter:	0.3000 mm
Copper Finish:	ENIG	Impedance Control:	Yes
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Remy Nguyen | D

Sheet:
File: 002.35.20.15.20-001-PCB-LNA.kicad_pcb

Title: RF-DFS Gain Circuit		
Size: USLetter	Date: 2/23/2024	Rev: C
KiCad E.D.A. kicad 7.0.5		Id: 1/1